

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

SS52C THRU SS510C

Product specification


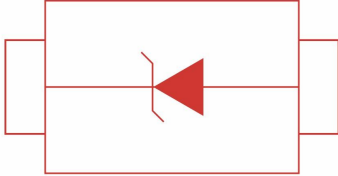
Features

- Ideal for surface mount applications
- Easy pick and place
- Built-in strain relief
- Low forward voltage drop

MECHANICAL DATA

- Case: Molded plastic
- Epoxy: UL 94V-0 rate flame retardant
- Metallurgically bonded construction
- Polarity: Color band denotes cathode end
- Mounting position: Any
- Weight: 0.21 grams

Reference News

PACKAGE OUTLINE	Pin Configuration
	
SMC	

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25 °C ambient temperature unless otherwise specified.
 Single phase half wave, 60Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

P/N(MARK)	SS52C	SS53C	SS54C	SS55C	SS56C	SS58C	SS59C	SS510C	UNITS
Maximum Recurrent Peak Reverse Voltage	20	30	40	50	60	80	90	100	V
Maximum RMS Voltage	14	21	28	35	42	56	63	70	V
Maximum DC Blocking Voltage	20	30	40	50	60	80	90	100	V
Maximum Average Forward Rectified Current at T _L =90 C	5.0								A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	150								A
Maximum Instantaneous Forward Voltage at 5.0A	0.55			0.70		0.85			V
Maximum DC Reverse Current at Rated DC Blocking Voltage	Ta=25 C		0.1			0.02			mA
	Ta=100 C		5			2			mA
Typical Junction Capacitance (Note1)	300								pF
Typical Thermal Resistance R _{JL} (Note 2)	10								C/W
Operating Temperature Range T _J	-65 — +150								°C
Storage Temperature Range T _{STG}	-65 — +150								°C

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Lead.

RATING AND CHARACTERISTIC CURVES (SS52C THRU SS510C)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

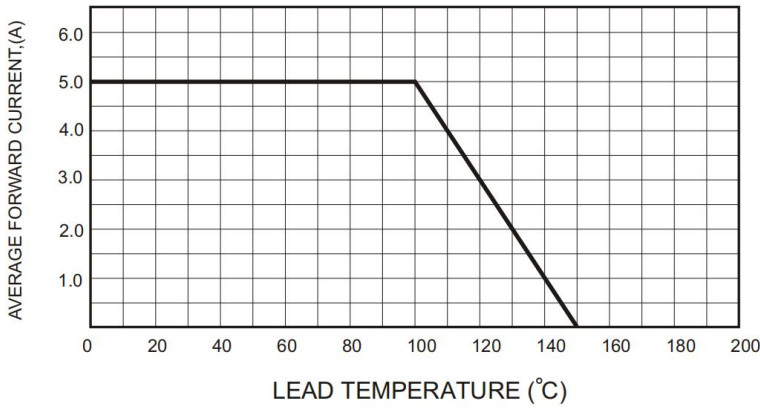


FIG.2-TYPICAL FORWARD CHARACTERISTICS

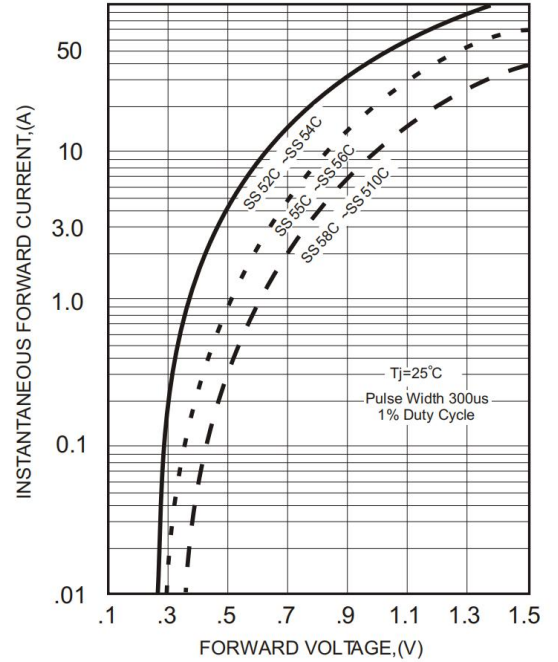


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

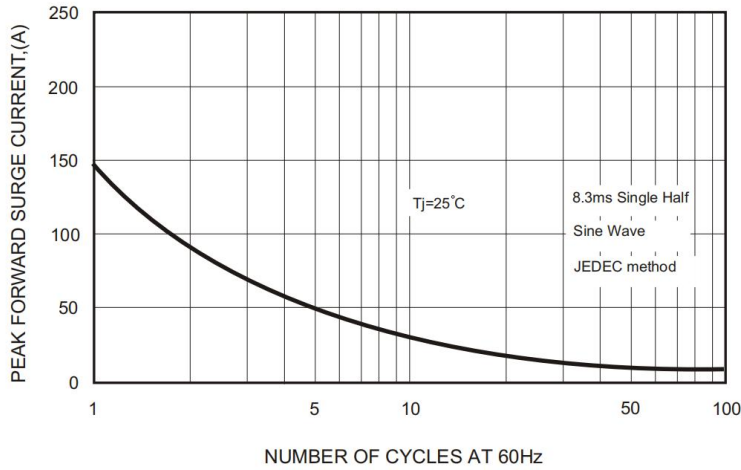


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

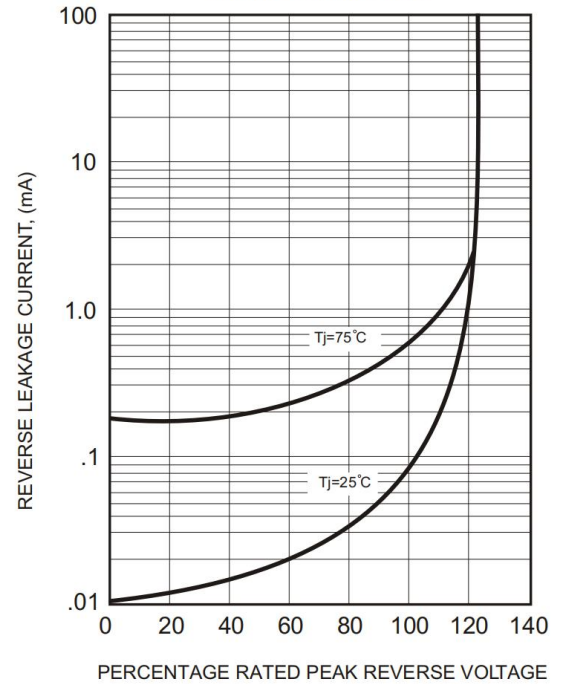
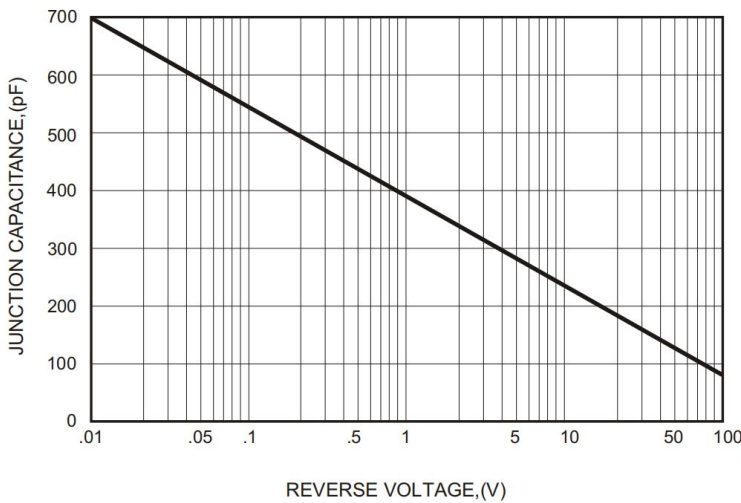
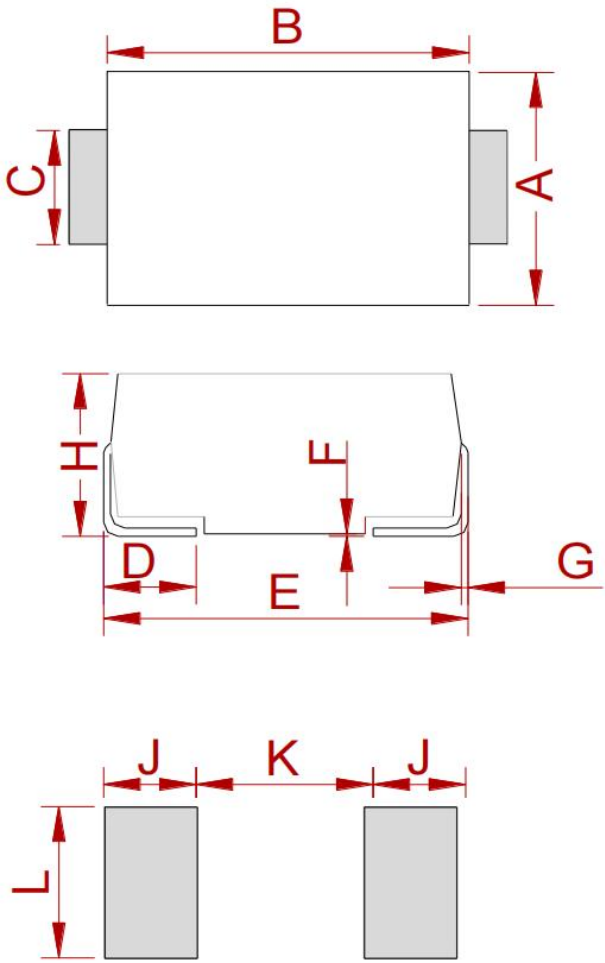


FIG.4-TYPICAL JUNCTION CAPACITANCE



PACKAGE MECHANICAL DATA



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	5.75	6.25	0.226	0.246
B	6.90	7.40	0.272	0.291
C	2.75	3.25	0.108	0.128
D	0.95	1.52	0.037	0.060
E	7.70	8.20	0.303	0.323
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.15	2.62	0.085	0.103
J	2.40		0.094	
K		4.20		0.165
L	3.30		0.130	

DO-214AB (SMC)

REEL SPECIFICATION

P/N	PKG	QTY
SS52C THRU SS510C	SMC	3000

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